Product name:	Product code:
Internal Bond Strength Tester for Paperboard	CMI-IND-0109

Description

Measures the force needed to delaminate paperboard in the Z direction using a pendulum impact on a bonded specimen block. Used by board mills and converters to detect ply separation, picking and die-cutting issues.

Technical specification

Construction	Cast iron frame with powder coating

Standard Accessories

- Aluminium bond plate set
- Double-sided tape roll
- Specimen press

A board specimen is bonded between two aluminium angle plates and struck by a pendulum, and the energy absorbed in splitting the sheet is read from the scale or digital encoder. Low internal bond values predict blistering during heat sealing, delamination on creasing and surface picking in offset printing. The tester gives quick comparison between lots and between mill suppliers.

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Features

- Scott type pendulum with digital angle encoder
- Direct readout in J/m2 or ft.lbf x 10-3/in2
- Specimen bonding fixture for consistent sample prep
- Selectable pendulum weights for different strength ranges
- Quick lock and release of the specimen holder

Technical Specifications

Measuring Range	0 - 400 J/m2 (extendable with weights)
Resolution	0.1 J/m2
Specimen Size	25.4 mm x 25.4 mm bond area
Pendulum Type	Scott type, steel with locking latch
Accuracy	+/- 1 %
Standards	TAPPI T569, TAPPI UM 403
Display	Digital LCD
Power Supply	230 V AC, 50 Hz